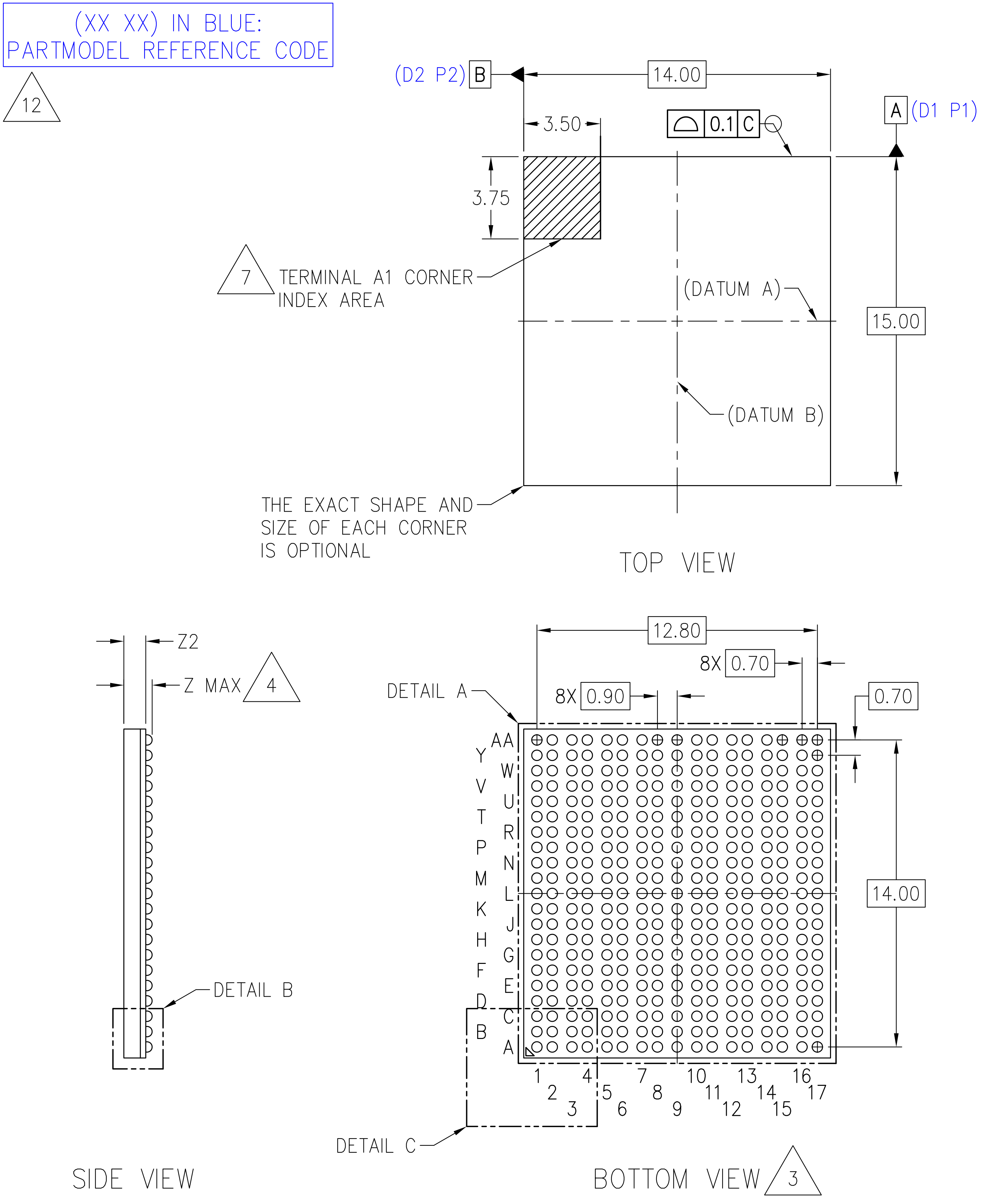
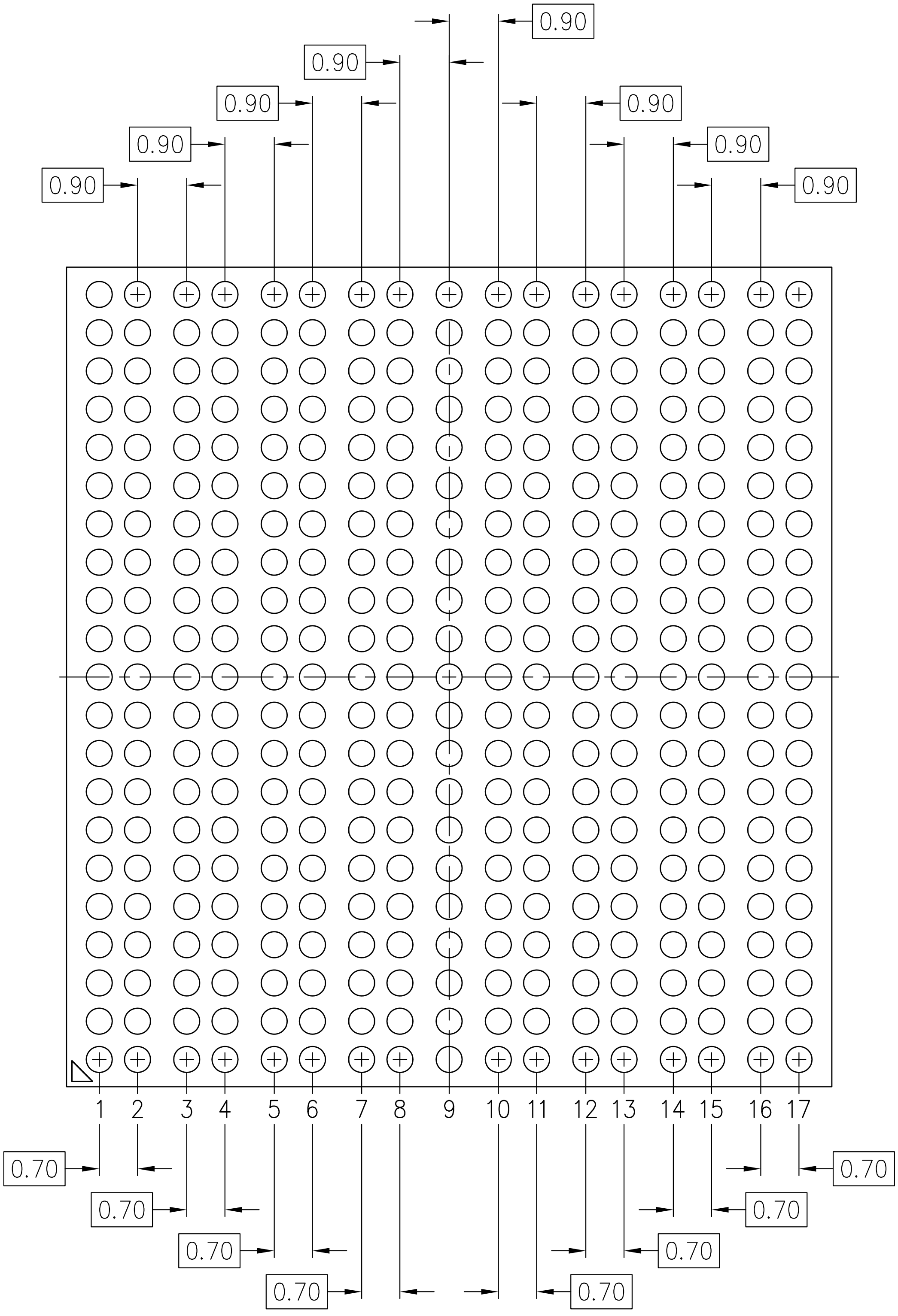


JEDEC SOLID STATE PRODUCT OUTLINE	THIS *REGISTERED OUTLINE* WAS PREPARED BY THE JEDEC JC-11 COMMITTEE AND REFLECTS A PRODUCT FOR ANTICIPATED USE IN THE ELECTRONICS INDUSTRY. CHANGES ARE LIKELY TO OCCUR. USERS ASSUME ALL RISK AND LIABILITY RESULTING FROM THE USE OF THIS OUTLINE.

TITLE	PACKAGE DESIGNATOR	ITEM	ISSUE	DATE	SHEET
PLASTIC BOTTOM GRID ARRAY, BALL, 0.70/0.90 MM X 0.70 MM PITCH, RECT FAMILY PACKAGE	PBGA-B#[#] I0p7...	MO-369	A	JAN 2026	1 OF 5



DETAIL A

JEDEC SOLID STATE PRODUCT OUTLINE	TITLE PLASTIC BOTTOM GRID ARRAY, BALL, 0.70/0.90 MM X 0.70 MM PITCH, RECT FAMILY PACKAGE	ITEM	ISSUE	DATE	SHEET
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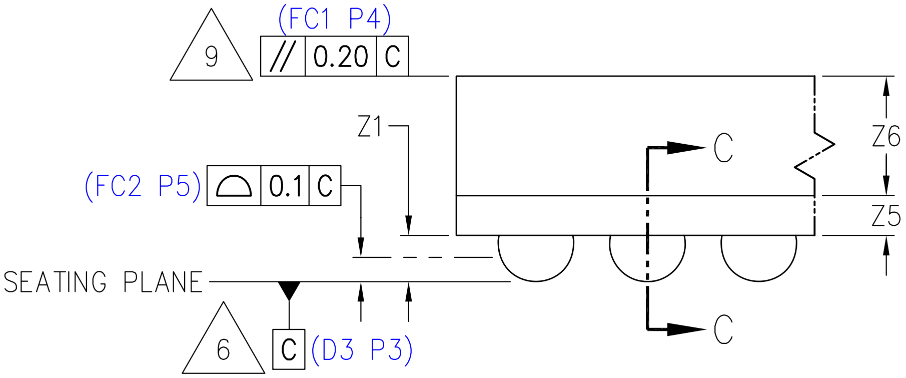
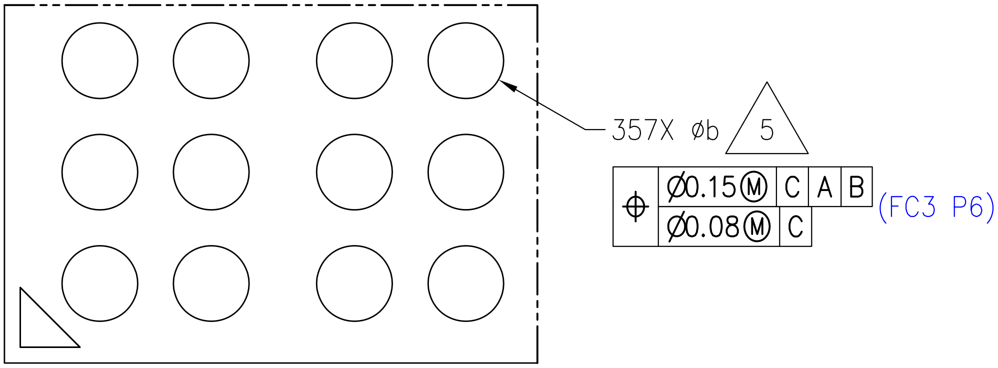
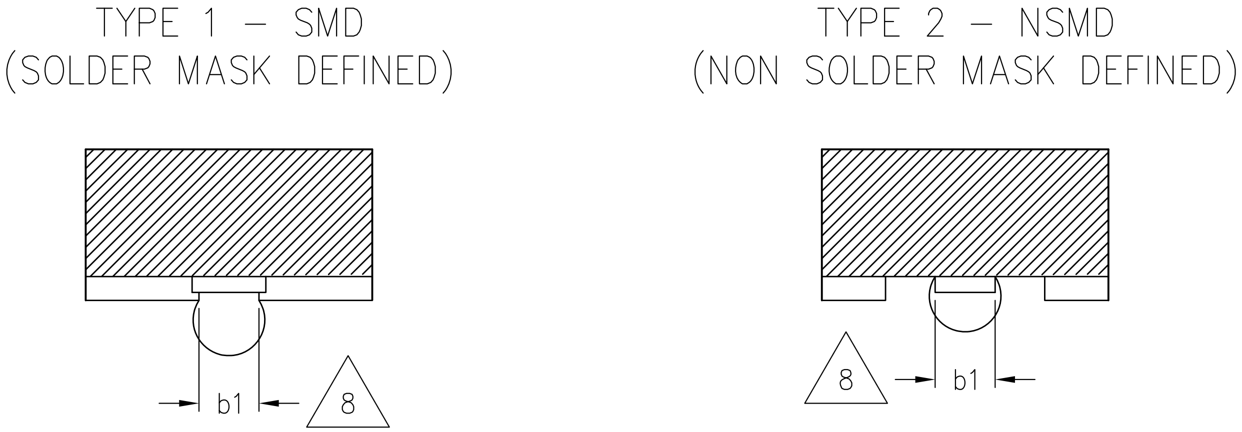


DETAIL B
(ROTATED 90° CW)



DETAIL C


TYPE 1 – SMD
(SOLDER MASK DEFINED)

TYPE 2 – NSMD
(NON SOLDER MASK DEFINED)

SECTION C–C

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TABLE 1

COMMON DIMENSIONS		
SYMBOL		
Z		PACKAGE SPECIFIC
Z2	b(NOM) = 0.475	Z2(MAX) = Z(MAX) − Z1
Z5		OPTIONAL − PACKAGE SPECIFIC
Z6		OPTIONAL − PACKAGE SPECIFIC
NOTES		1, 2, 4
REF		11−1100
ISSUE		A

TABLE 2

COMMON DIMENSIONS				
SYMBOL		SOLDER BALL DIAMETER		
		MIN	NOM	MAX
Z1		PACKAGE SPECIFIC	−−−	−−−
b		0.400	0.475	0.550
b1	TYPE 1	0.31	−−−	−−−
	TYPE 2	0.31	−−−	−−−
NOTES		1, 2, 10		
REF		11−1100		
ISSUE		A		

b1 = b(NOM) * 0.667

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NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5-2009. THIS OUTLINE CONFORMS TO JEP95, SECTION 4.5.

2. ALL DIMENSIONS ARE IN MILLIMETERS.

3 SOLDER BALL POSITION DESIGNATION PER JEP95 SECTION 3, SPP-010.

4 DIMENSION Z INCLUDES STAND-OFF HEIGHT Z1, PACKAGE BODY THICKNESS AND LID HEIGHT, BUT DOES NOT INCLUDE ATTACHED FEATURES, e.g., EXTERNAL HEATSINK. AN INTEGRAL HEATSLUG IS NOT CONSIDERED AN ATTACHED FEATURE.

5 DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO PRIMARY DATUM C.

6 PRIMARY DATUM C (SEATING PLANE) IS DEFINED BY THE PLANE ESTABLISHED BY THE CONTACT POINTS OF THREE OR MORE SOLDER BALLS THAT SUPPORT THE DEVICE WHEN IT IS PLACED ON TOP OF A PLANAR SURFACE.

7 THE A1 TERMINAL CORNER MUST BE IDENTIFIED ON BOTH THE BOTTOM AND TOP SIDES OF THE PACKAGE, THE IDENTIFICATION FEATURE CAN BE MADE USING INK, METALIZED MARKINGS, IDENTATIONS, OR OTHER FEATURES.

8 THE SOLDERABLE SURFACE MAY BE DEFINED BY AN OPENING IN THE SOLDER RESIST LAYER (TYPE 1) OR BY THE SIZE OF A METALIZED PAD (TYPE 2). IT MAY BE ELLIPITACL PROVIDED THE RATIO OF THE MAJOR TO MINOR AXES IS NO GREATER THAN 2/1, AND THE SURFACE AREA IS NO LESS THEN THE MINIMUM FOR A CIRCULAR PAD. FOR TYPE 2 DESIGNS, EXPOSED COPPER TRACES ARE PERMITTED OUTSIDE THE b1 PAD AREA.

9 FOR GLOB TOP AND FLIP CHIP CONFIGURATIONS, PARALLELISM (ccc) APPLIES ONLY TO THE SURFACE DIRECTLY ABOVE THE DIE AREA. THE PARALLELISM SPECIFICALLY WILL NOT APPLY TO ANY FILLET OR SLOPED REGION OF THE ENCAPSULANT.

10. SEE JESD30 FOR EXPLANATION OF VARIATION SCHEME/PACKAGE DESIGNATOR. PACKAGE HEIGHT IS THE MAXIMUM PACKAGE THICKNESS.

11. THE Z1 HEIGHT NEEDS TO BE ACCEPTABLE TO MANUFACTURING STANDARDS.

12 (XX XX) IN BLUE: PARTMODEL REFERENCE CODE
D# = DATUM ID#
FC# = FEATURE CONTROL FRAME ID#
P# = PLACEMENT ID#

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STP (3D) FILE RECORD

3D FILE NAMES MAY EXCEED LENGTH REQUIREMENTS FOR SOME SOFTWARE TOOLS.

STP FILE NAME	DATE	ITEM NUMBER
MO-369A_PBGA-B357_I0p70-R14p0x15p0Z#-C0p475H#	JAN 2026	11-1100

JEDEC SOLID STATE
PRODUCT OUTLINE

TITLE	ITEM	ISSUE	DATE	SHEET
PLASTIC BOTTOM GRID ARRAY, BALL, 0.70/0.90 MM X 0.70 MM PITCH, RECT FAMILY PACKAGE	MO-369	A	JAN 2026	i

TASK GROUP CONTRIBUTORS

INTEL CORPORATION
MICRON TECHNOLOGY INC.

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CHANGE RECORD

IF THE CHANGE INVOLVES ANY WORDS ADDED OR DELETED (EXCLUDING DELETION OF ACCIDENTALLY REPEATED WORDS), THE CHANGE IS TO BE INCLUDED BELOW. PUNCTUATION CHANGES MAY OR MAY NOT BE INCLUDED.

INITIAL ISSUE: A	DATE: JANUARY 2026	ITEM NUMBER: 11–1100

CHANGE RECORD HISTORY:

ISSUE: –	DATE: –	ITEM NUMBER: –

LOCATION	CHANGED FROM:	CHANGED TO:

JEDEC SOLID STATE PRODUCT OUTLINE	TITLE	ITEM	ISSUE	DATE	SHEET
	PLASTIC BOTTOM GRID ARRAY, BALL, 0.70/0.90 MM X 0.70 MM PITCH, RECT FAMILY PACKAGE	MO-369	A	JAN 2026	